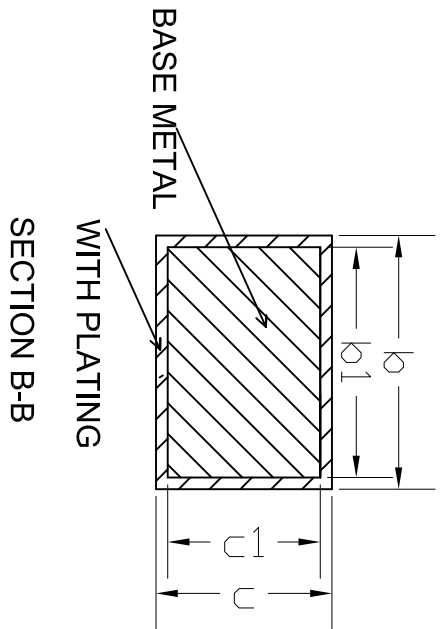
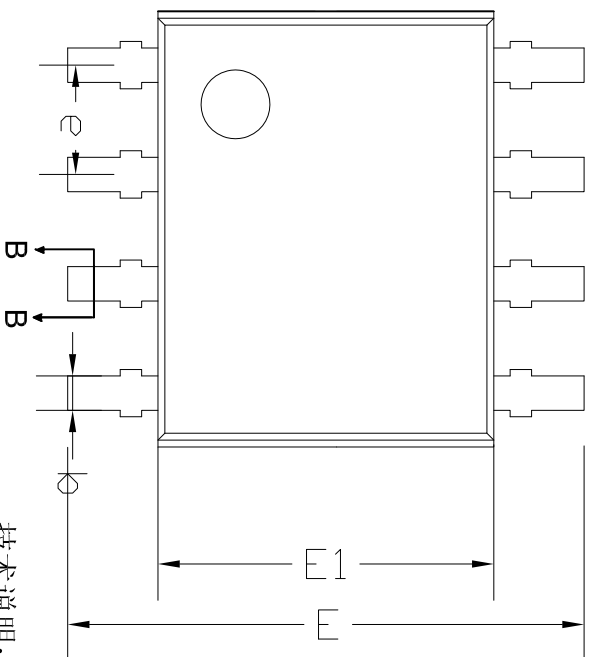
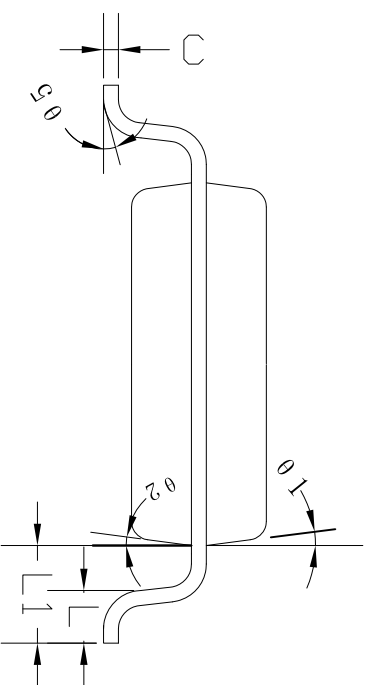
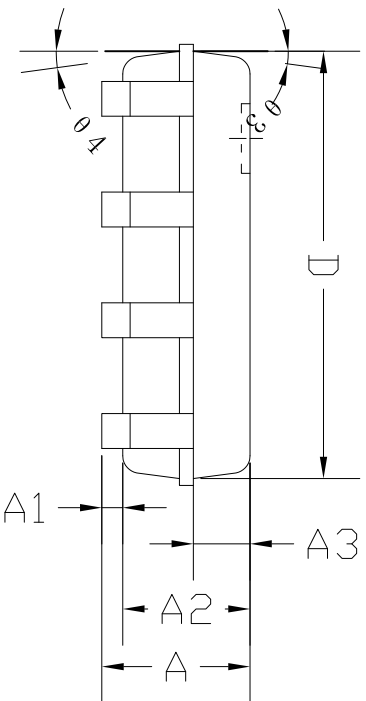


# SOP8 PACKAGE OUTLINE DIMENSIONS



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	--	--	1.65
A1	0.10	0.14	0.20
A2	1.40	1.42	1.50
A3	0.60	0.65	0.70
b	0.39	--	0.46
b1	0.38	0.41	0.44
c	0.20	--	0.24
c1	0.19	0.20	0.21
D	4.80	4.90	5.00
E	5.90	6.00	6.20
E1	3.85	3.90	4.00
e	1.27(BSC)		
L	0.50	0.60	0.70
L1	1.05(REF)		
$\theta 1$	6°	~	12°
$\theta 2$	6°	~	12°
$\theta 3$	5°	~	10°
$\theta 4$	5°	~	10°
$\phi$	0°	~	6°

- 技术说明:
- 1) LEADFRAME MATERIAL: COPPER;  
引线框架材料: 铜;
  - 2) LEADFRAME THICKNESS: 0.203mm;  
引线框架厚度: 0.203mm;
  - 3) BOTH PACKAGE LENGTH AND WIDTH DO NOT INCLUDE MOLD FLASH;  
塑封体长度及宽度尺寸不包括塑封溢胶;
  - 4) REFERENCE: JEDEC MS-013, MS-012。  
参考标准: JEDEC MS-013, MS-012。